<table>
<thead>
<tr>
<th>Layer Name</th>
<th>Top Solder</th>
<th>Top Solder Cap</th>
<th>Top Solder Ref</th>
<th>Pad ID</th>
<th>Component Type</th>
<th>Date</th>
<th>Time</th>
<th>Manufacturer</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER 1</td>
<td>Top Solder 1</td>
<td>Top Solder Cap1</td>
<td>Top Solder Ref1</td>
<td>PAC1</td>
<td>Component Type1</td>
<td>Date1</td>
<td>Time1</td>
<td>Manufacturer1</td>
</tr>
<tr>
<td>LAYER 2</td>
<td>Top Solder 2</td>
<td>Top Solder Cap2</td>
<td>Top Solder Ref2</td>
<td>PAC2</td>
<td>Component Type2</td>
<td>Date2</td>
<td>Time2</td>
<td>Manufacturer2</td>
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<tr>
<td>LAYER 3</td>
<td>Top Solder 3</td>
<td>Top Solder Cap3</td>
<td>Top Solder Ref3</td>
<td>PAC3</td>
<td>Component Type3</td>
<td>Date3</td>
<td>Time3</td>
<td>Manufacturer3</td>
</tr>
<tr>
<td>LAYER 4</td>
<td>Top Solder 4</td>
<td>Top Solder Cap4</td>
<td>Top Solder Ref4</td>
<td>PAC4</td>
<td>Component Type4</td>
<td>Date4</td>
<td>Time4</td>
<td>Manufacturer4</td>
</tr>
</tbody>
</table>

*Note: The table represents a layout of the PCB layers, including the top and bottom sides, with specific identifiers for pads, components, and other manufacturing data.*
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